

Side View LEDs (0.8mm) EAPL2812BA1



Features

- Side view LED.
- Lead frame package with individual 2 pins.
- Wide viewing angle.
- Soldering methods: IR reflow soldering.
- ESD protection
- Pb-free.
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).
- Precondition: Bases on JEDEC J-STD 020D Level 3

Descriptions

- Due to the package design, EAPL2812BA1 has wide viewing angle and low power consumption. Ideal for light guide application.

Applications

- LCD back light.
- Mobile phones .
- Indicators.
- Illuminations.
- Switch lights.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Blue	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	100	mA
Power Dissipation	P_d	110	mW
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +90	°C
ESD	ESD_{HBM}	2000	V
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Note: 1. The products are sensitive to static electricity and must be carefully taken when handling products.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	225	-----	565	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}	-----	110	-----	deg	I _F =20mA
Peak Wavelength	λ _p	-----	468	-----	nm	I _F =20mA
Dominant Wavelength	λ _d	464.5	-----	476.5	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ	-----	35	-----	nm	I _F =20mA
Forward Voltage	V _F	2.65	-----	3.25	V	I _F =20mA
Reverse Current	I _R	-----	-----	10	μA	V _R =5V

Notes:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.05V

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Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
S2	225	285	mcd	I _F =20mA
T1	285	360		
T2	360	450		
U1	450	565		

Note:

Tolerance of Luminous Intensity: ±11%

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
A9	464.5	467.5	nm	I _F =20mA
A10	467.5	470.5		
A11	470.5	473.5		
A12	473.5	476.5		

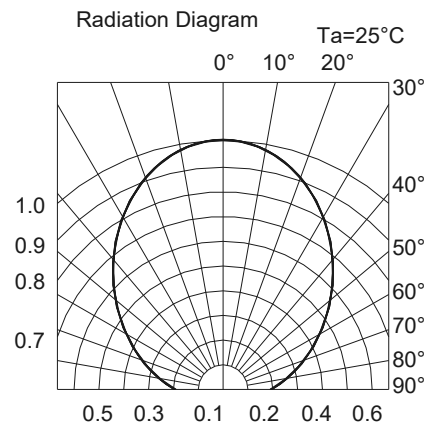
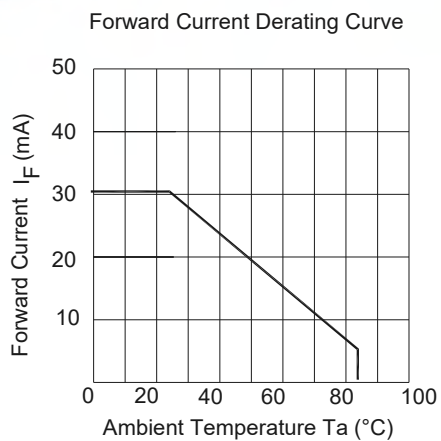
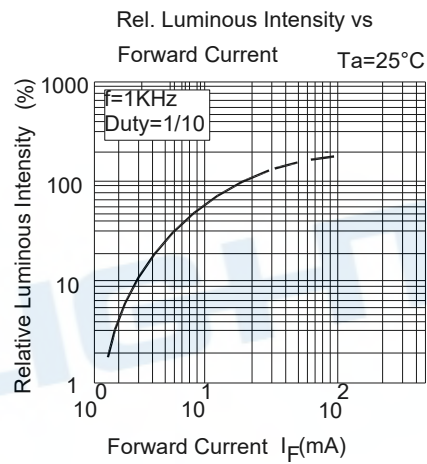
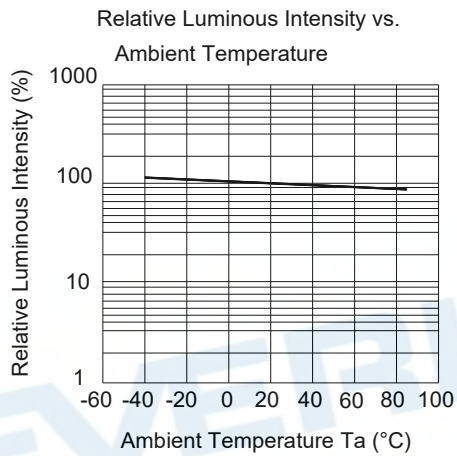
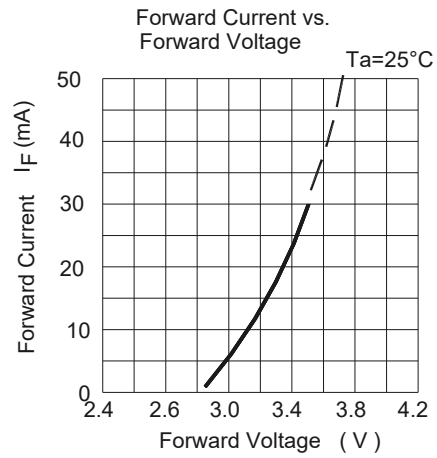
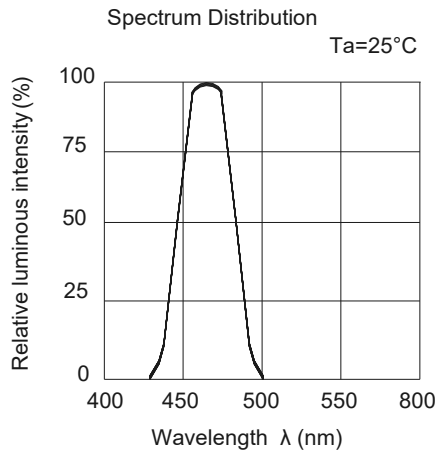
Note: Tolerance of Dominant Wavelength: ±1nm

Bin Range of Forward Voltage

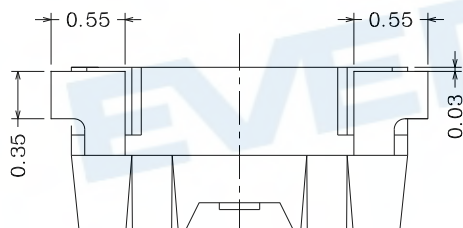
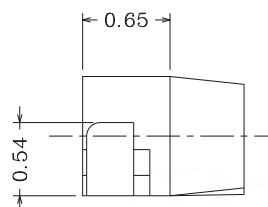
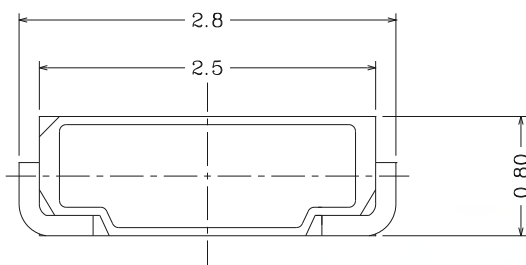
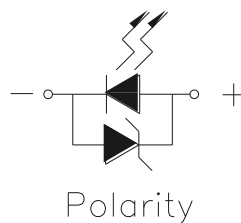
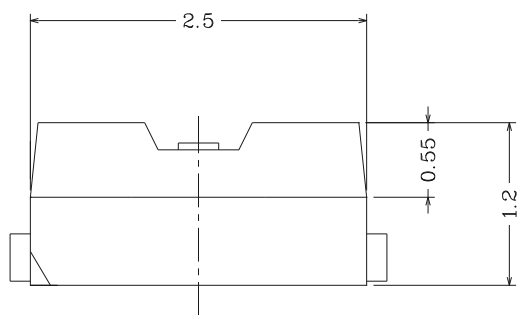
Bin Code	Min.	Max.	Unit	Condition
51	2.65	2.75	V	I _F =20mA
52	2.75	2.85		
53	2.85	2.95		
54	2.95	3.05		
55	3.05	3.15		
56	3.15	3.25		

Note: Tolerance of Forward Voltage: ±0.05V.

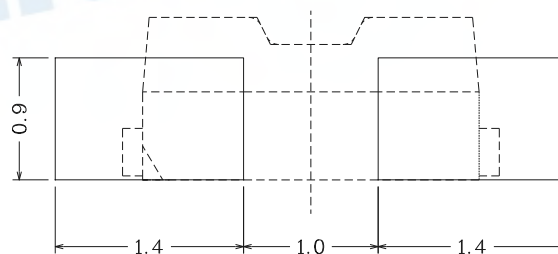
Typical Electro-Optical Characteristics Curves



Package Dimension



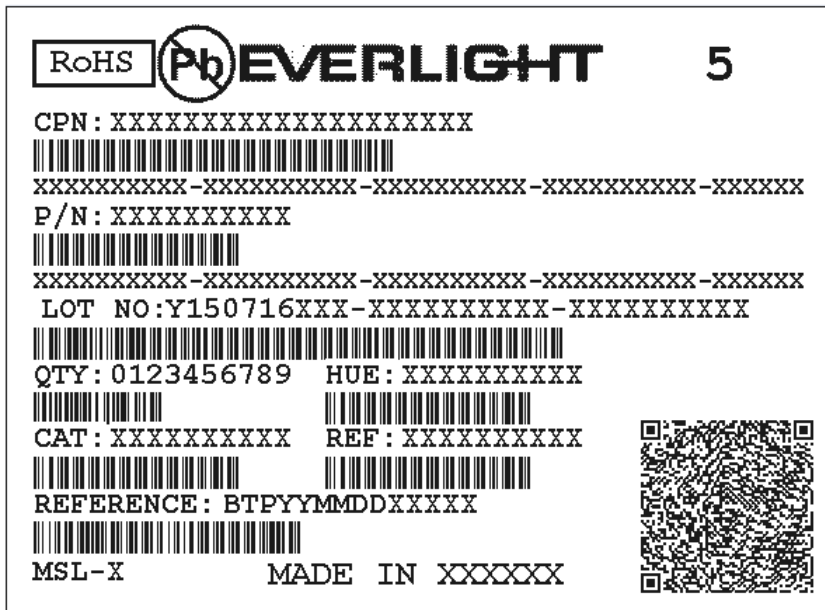
Recommended soldering pad design



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

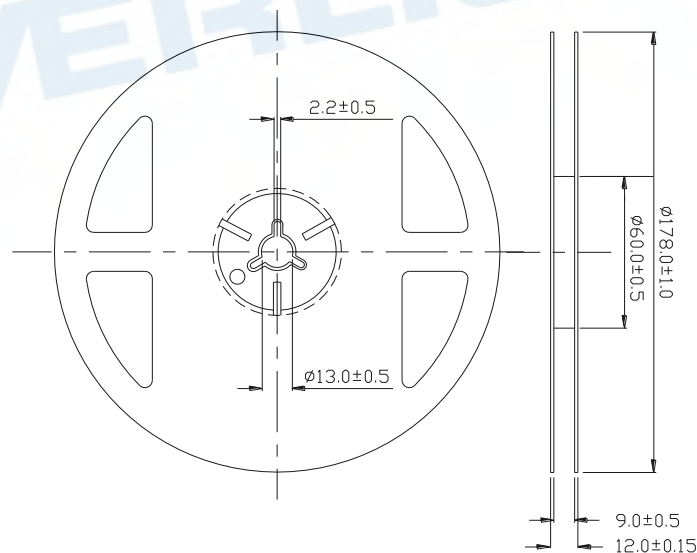
Moisture Resistant Packing Materials

Label Explanation



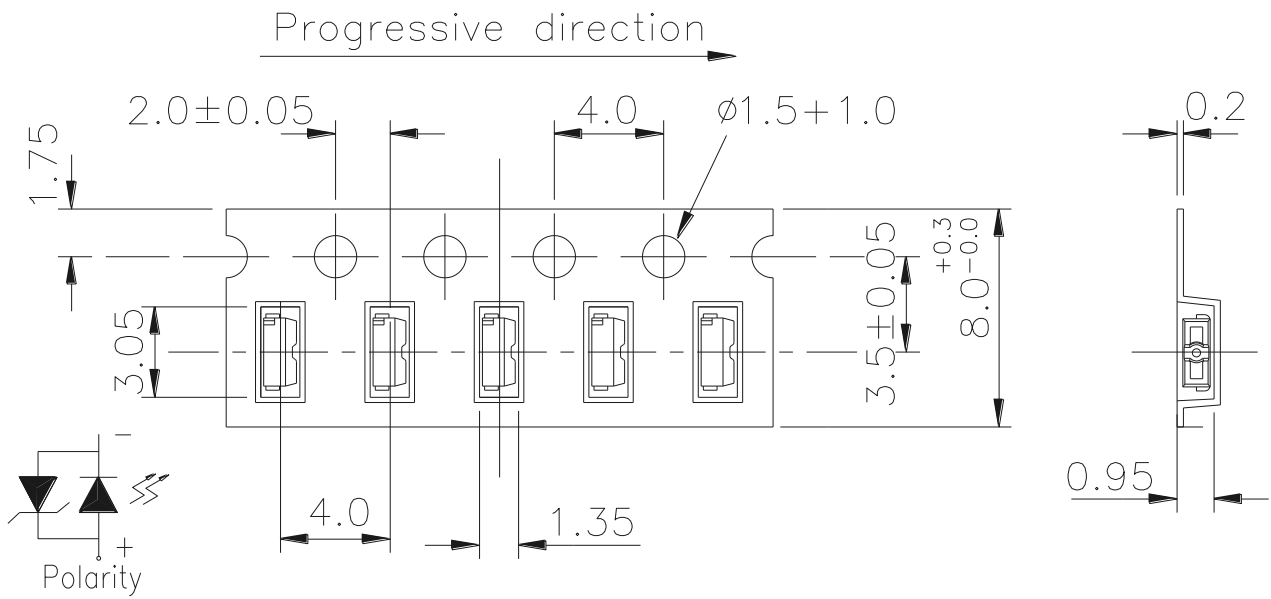
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number
- MADE IN TAIWAN: Production Place

Reel Dimensions



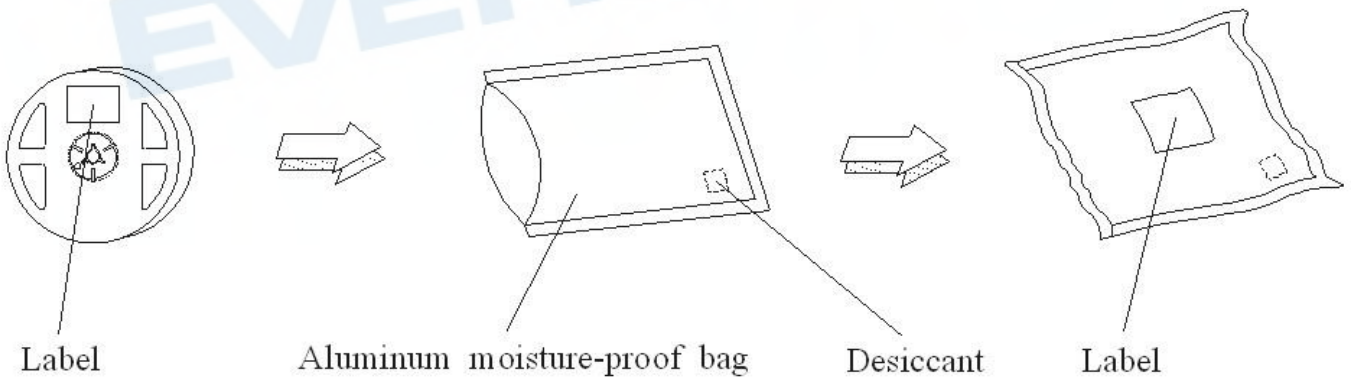
Note: The tolerances unless mentioned is : ±0.1mm, Unit = mm

Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note:
 Tolerances unless mentioned ± 0.1 mm. Unit = mm

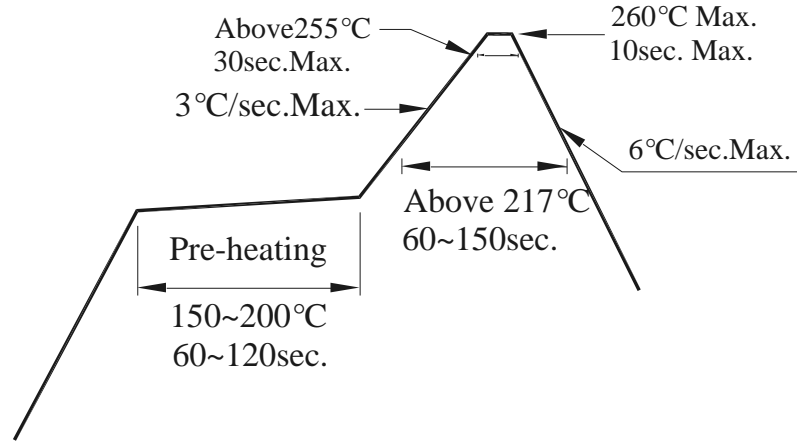
Moisture Resistant Packing Process



Precautions for Use

1. Over-current-proof

- 1.1 Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).



2. Storage

- 2.1 Moisture proof bag should only be opened immediately prior to usage.
2.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.
2.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.
2.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

3. Soldering Condition

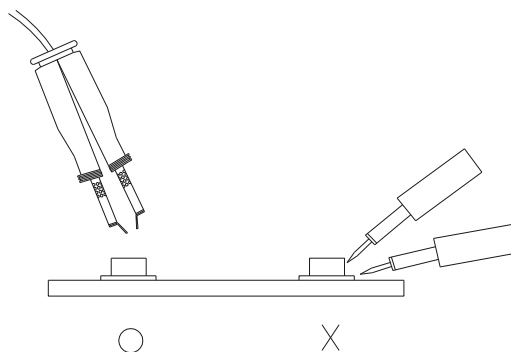
- 3.1 Pb-free solder temperature profile
3.2 Reflow soldering should not be done more than two times.
3.3 When soldering, do not put stress on the LEDs during heating.
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

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